

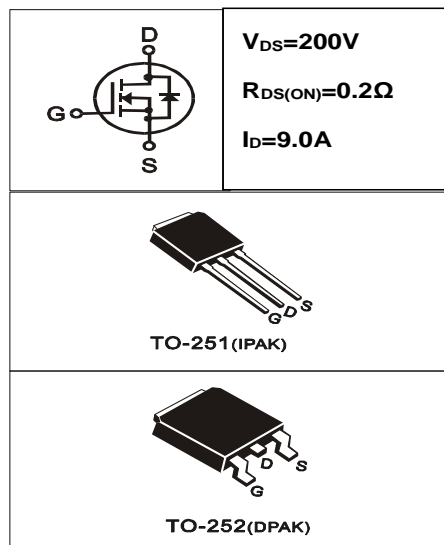
N-CHANNEL POWER MOSFET

Features

- LOW ON-RESISTANCE
- FAST SWITCHING
- HIGH INPUT RESISTANCE
- RoHS COMPLIANT

Applications

- LIGHTING
- UNINTERRUPTED POWER SUPPLY
- SWITCH MODE POWER SUPPLY
- AC-DC CONVERSION CIRCUIT



● Absolute Maximum Ratings (Tc=25 °C)

PARAMETER	SYMBOL	VALUE	UNIT
Drain-source Voltage	V_{DS}	200	V
gate-source Voltage	V_{GS}	± 20	V
Continuous Drain Current TC=25°C	I_D	9	A
Continuous Drain Current TC=100°C	I_D	4.5	A
Drain Current — Pulsed ①	I_{DM}	36	A
Power Dissipation	P_{tot}	100	w
Junction Temperature	T_j	150	°C
Storage Temperature	T_{STG}	-55-150	°C
Single Pulse Avalanche Energy ②	E_{AS}	270	mJ

● Electronic Characteristics (Tc=25°C)

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Drain-source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	200			V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_j$	$I_D=250\mu A$, Referenced to 25°C		0.2		V/°C
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.5		2.5	V
Drain-source Leakage Current	I_{DSS}	$V_{DS}=200V, V_{GS}=0V, T_j=25^\circ C$			1	μA
		$V_{DS}=200V, V_{GS}=0V, T_j=125^\circ C$			10	μA
Forward Transconductance	G_{FS}	$V_{DS}=10V, I_D=9A$ ③	5.0	9.5		S



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• Electrical Characteristics

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Gate-body Leakage Current ($V_{DS} = 0$)	I_{GSS}	$V_{GS} = \pm 20V$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 4.0A$ ③		0.22	0.45	Ω
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 4.5A$ ③		0.20	0.40	Ω
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V$ $F = 1.0MHz$		815		pF
Output Capacitance	C_{oss}				120	pF
Miller Capacitance	C_{rss}				25	pF
Turn -Off Delay Time	$T_d(off)$	$V_{DD} = 100V, I_D = 9.0A$ $R_G = 3.5\Omega, R_D = 25\Omega$ ③		35		ns
Total Gate Charge	Q_g	$I_D = 9.0A, V_{DS} = 160V$ $V_{GS} = 10V$ ③		16.5		nC
Gate-to-Source Charge	Q_{gs}				2.5	nC
Gate-to-Drain Charge	Q_{gd}				3.8	nC
Continuous Diode Forward Current	I_s				9.0	A
Diode Forward Voltage	V_{SD}	$T_j = 25^\circ C, I_s = 9.0A$ $V_{GS} = 0V$ ③			1.45	V
Reverse Recovery Time	t_{rr}	$T_j = 25^\circ C, I_f = 9.0A$ $di/dt = 100A/\mu s$ ③			128	ns
Reverse Recovery Charge	Q_{rr}				655	nC

• Thermal Characteristics

PARAMETER	SYMBOL	MAX	UNIT
Thermal Resistance Junction-case	R_{thJC}	1.25	$^\circ C/W$
Thermal Resistance Junction-ambient	R_{thJA}	62.5	$^\circ C/W$

(Notes):

- ① Repetitive rating: Pulse width limited by maximum junction temperature
- ② Starting $T_j = 25^\circ C, V_{DD} = 50V, L = 3.0 mH, R_G = 25\Omega, I_{AS} = 9.0A$
- ③ Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$

Typical Performance Characteristics

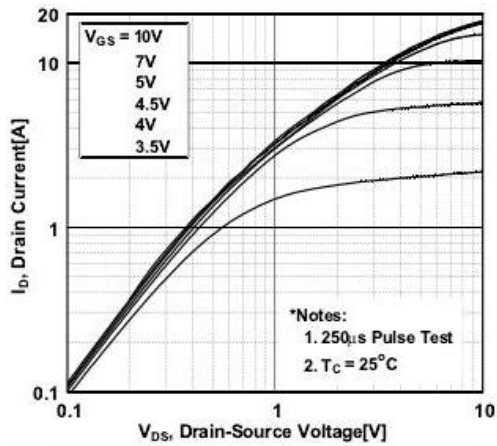


Fig1 Typical Output Characteristics, $T_C = 25^\circ\text{C}$

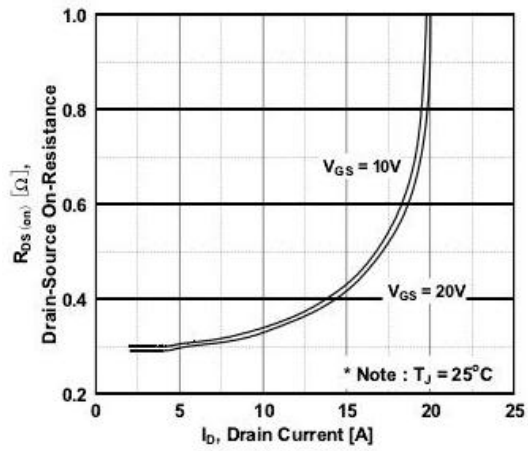


Fig2 On-Resistance Vs. Drain Current and Gate Voltage

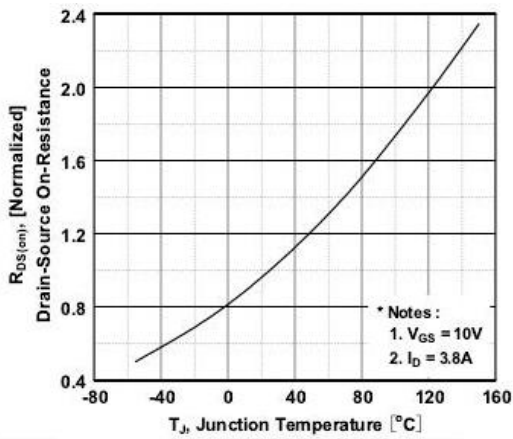


Fig3 Normalized On-Resistance Vs. Temperature

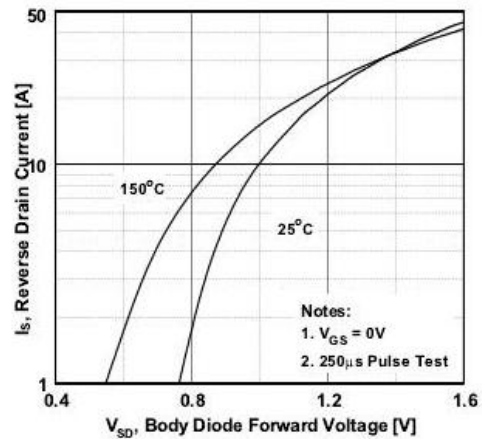


Fig4 Typical Source-Drain Diode Forward Voltage

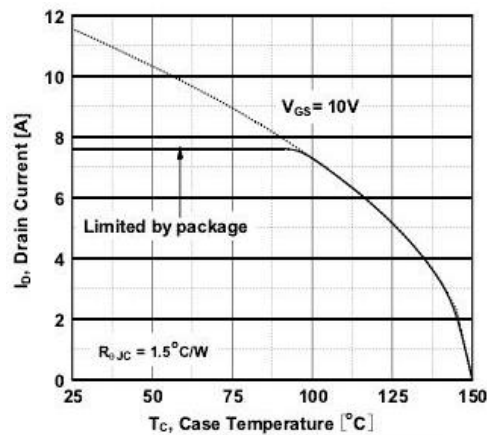


Fig5 Maximum Drain Current Vs. Case Temperature

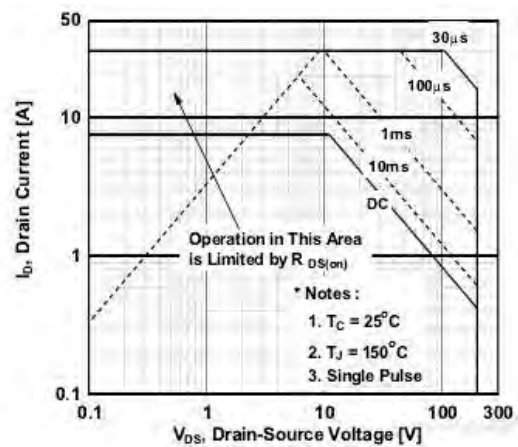


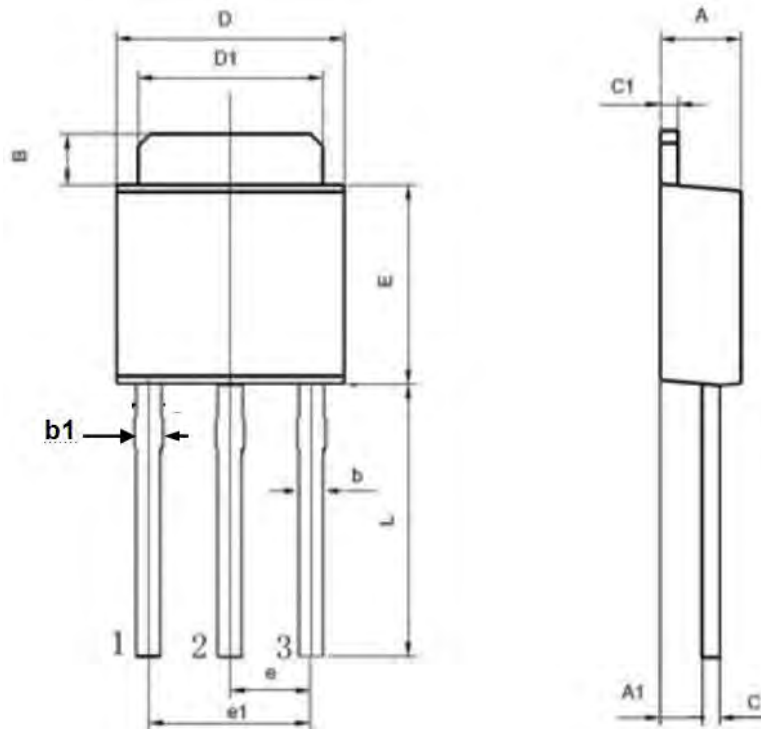
Fig6 Maximum Safe Operating Area

TO-251 (IPAK) MECHANICAL DATA

UNIT: mm

SYMBOL	min	nom	max
A	2.10		2.50
A ₁	0.95		1.30
B	0.80		1.25
b	0.50		0.80
b ₁	0.70		0.90
c	0.45		0.70
c ₁	0.45		0.70
D	6.35		6.80
D ₁	5.10		5.50
E	5.30		6.30
e		2.30	
L	7.00		9.20
R		0.30	

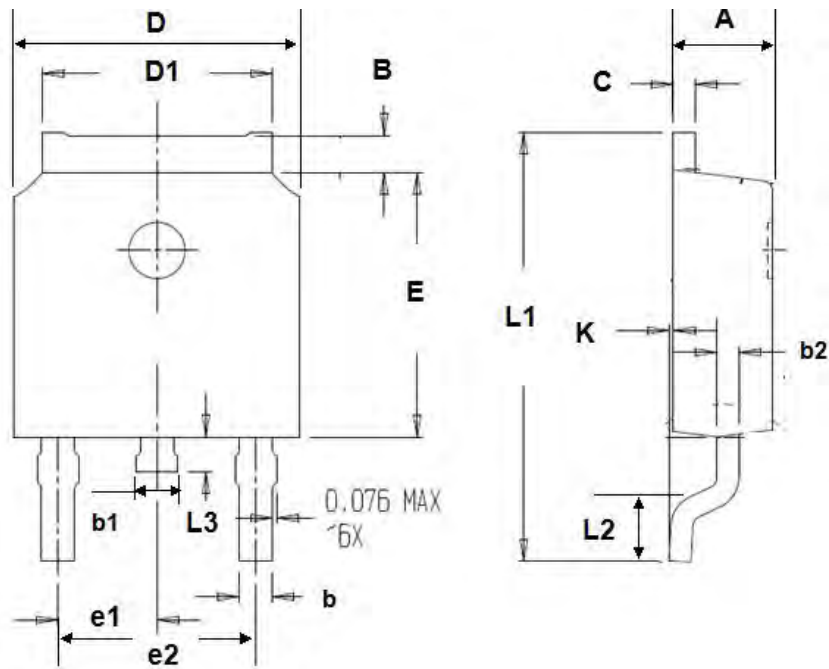
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TO-252 MECHANICAL DATA

UNIT: mm

SYMBOL	min	max	SYMBOL	min	max
A	2.10	2.50	B	0.85	1.25
b	0.50	0.80	b1	0.70	1.20
b2	0.45	0.70	C	0.45	0.70
D	6.30	6.75	D1	5.10	5.50
E	5.30	6.30	e1	2.25	2.35
L1	9.20	10.60	e2	4.45	4.75
L2	0.90	1.75	L3	0.60	1.10
K	0.00	0.23			



TO-252 TAPE AND REEL DATA

UNIT: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A0	6.80	6.90	7.00	B0	10.40	10.50	10.60
K0	2.60	2.70	2.90	K1	2.40	2.50	2.60
F	7.40	7.50	7.60	K2	1.60	1.70	1.80
W	15.90	16.00	16.10	P1	7.90	8.00	8.10

